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Silicon Carbide Schottky Diode

650 V, 4 A

FFSM0465A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 23 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- This Device is Pb–Free, Halogen Free/BFR Free and RoHS Compliant

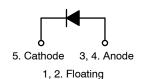
Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

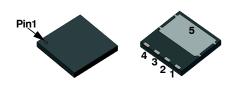


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Schottky Diode



PQFN 8×8, 2P CASE 483AP

MARKING DIAGRAM

\$Y&Z&3&K FFSM 0465A

\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = Lot Code FFSM0465A = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FFSM0465A

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C unless otherwise noted)

Symbol	Parameter	Value	Unit	
V_{RRM}	Peak Repetitive Reverse Voltage		650	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		23	mJ
l _F	Continuous Rectified Forward Current @ T _C < 152°C		4	А
	Continuous Rectified Forward Current @ T _C < 1	5.7		
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	320	А
		T _C = 150°C, 10 μs	310	Α
I _{F,SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	21	Α
I _{F,RM}	Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	15	Α
Ptot	Power Dissipation	T _C = 25°C	43	W
		T _C = 150°C	7.2	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max	3.5	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 4 A, T _C = 25°C	-	1.50	1.75	V
		I _F = 4 A, T _C = 125°C	_	1.6	2.0	
		I _F = 4 A, T _C = 175°C	_	1.72	2.4	
I _R	Reverse Current	V _R = 650 V, T _C = 25°C	-	-	200	μΑ
		V _R = 650 V, T _C = 125°C	-	-	400	
		V _R = 650 V, T _C = 175°C	-	-	600	
Q_{C}	Total Capacitive Charge	V = 400 V	-	15	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	247	-	pF
		V _R = 200 V, f = 100 kHz	-	29	-	
		V _R = 400 V, f = 100 kHz	-	22	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

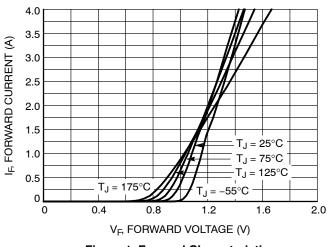
Part Number	Top Marking	Package	Shipping [†]
FFSM0465A	FFSM0465A	PQFN 8x8, 2P (Pb-Free/Halogen Free)	3000Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{1.} E_{AS} of 23 mJ is based on starting T_J = 25°C, L = 1 mH, I_{AS} = 6.8 A, V = 50 V.

FFSM0465A

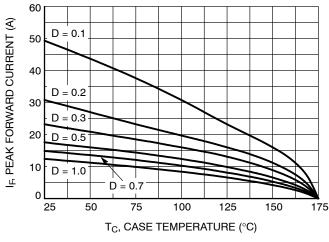
TYPICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)



10³ REVERSE CURRENT (µA) 10² 10¹ $T_J = 175^{\circ}C$ 100 $T_J = 25^{\circ}C$ 10^{-1} $T_J = 125$ °C <u>~</u> 10⁻² $T_J = 75^{\circ}C$ $T_{.1} = -55^{\circ}C$ 10⁻³ 700 100 200 400 500 800 V_R, REVERSE VOLTAGE (V)

Figure 1. Forward Characteristics

Figure 2. Reverse Characteristics



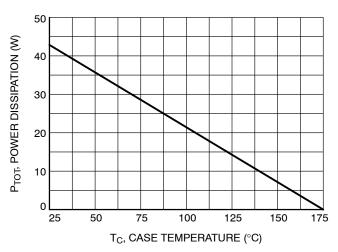
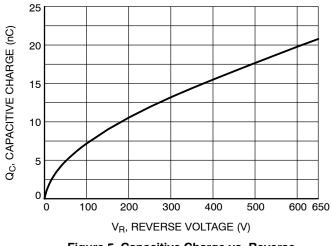


Figure 3. Current Derating

Figure 4. Power Derating



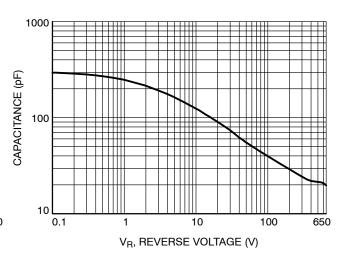


Figure 5. Capacitive Charge vs. Reverse Voltage

Figure 6. Capacitance vs. Reverse Voltage

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TYPICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

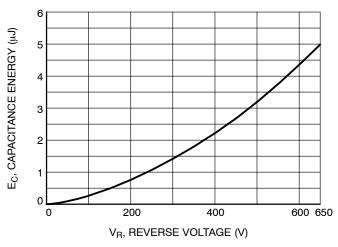


Figure 7. Capacitance Stored Energy

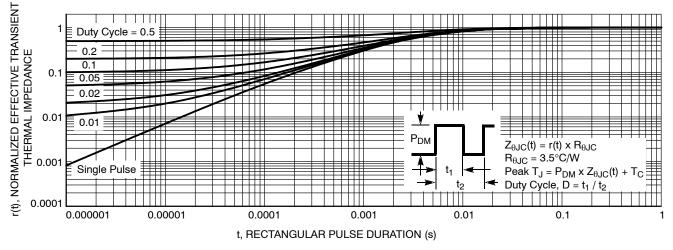


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

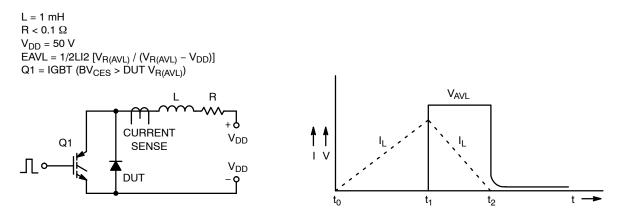
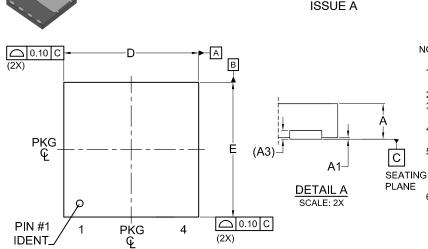


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform



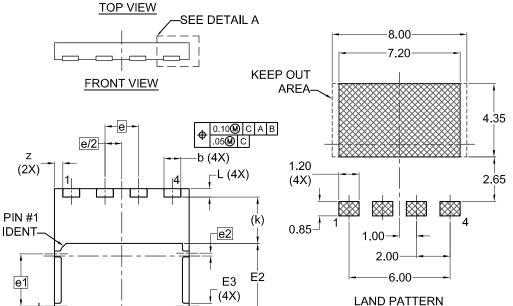


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DATE 06 JUL 2021

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
- SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.



(D3) (2X)

DIM	MILLIMETERS				
Diivi	MIN.	NOM.	MAX.		
Α	0.90	1.00	1.10		
A1	0.00	-	0.05		
А3	0.20 REF				
b	0.90	1.00	1.10		
D	7.90	8.00	8.10		
D2	7.10	7.20	7.30		
D3	0.40 REF				
E	7.90	8.00	8.10		
E2	4.25	4.35	4.45		
E3	0.25	0.35	0.45		
E4	0.40 REF				
е	2.00 BSC				
e/2	1.00 BSC				
e1	3.10 BSC				
e2	0.17 BSC				
k	2,75 REF				
L	0.40	0.50	0.60		

RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	PQFN4 8X8, 2P		PAGE 1 OF 1

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D2

BOTTOM VIEW

(E4)-

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